

Day : Monday  
Date: 1/31/2005

Time: 16:37:27


**PALM INTRANET**

## Inventor Name Search Result

Your Search was:

Last Name = GORMLEY

First Name = COLIN

Application#	Patent#	Status	Date Filed	Title	Inventor Name 12
<u>60396272</u>	Not Issued	159	07/16/2002	METHOD FOR FORMING A MICRO-MECHANICAL COMPONENT IN A SEMICONDUCTOR WAFER	GORMLEY, COLIN STEPHEN
<u>60342597</u>	Not Issued	159	12/20/2001	METHOD FOR ETCHING A TAPERED BORE IN A SILICON SUBSTRATE	GORMLEY, COLIN STEPHEN
<u>10952056</u>	Not Issued	030	09/28/2004	METHOD FOR FORMING A SEMICONDUCTOR DEVICE, AND A SEMICONDUCTOR DEVICE FORMED BY THE METHOD	GORMLEY, COLIN STEPHEN
<u>10786426</u>	Not Issued	030	02/25/2004	SEMICONDUCTOR WAFER COMPRISING MICRO-MACHINED COMPONENTS AND A METHOD FOR FABRICATING THE SEMICONDUCTOR WAFER	GORMLEY, COLIN STEPHEN
<u>10699503</u>	Not Issued	030	10/31/2003	METHOD FOR FORMING A FILLED TRENCH IN A SEMICONDUCTOR LAYER OF A SEMICONDUCTOR SUBSTRATE, AND A SEMICONDUCTOR SUBSTRATE WITH A SEMICONDUCTOR LAYER HAVING A FILLED TRENCH THEREIN	GORMLEY, COLIN STEPHEN
<u>10617427</u>	Not Issued	030	07/11/2003	METHOD FOR FORMING A MICRO-MECHANICAL COMPONENT IN A SEMICONDUCTOR WAFER, AND A SEMICONDUCTOR WAFER COMPRISING A MICRO-MECHANICAL	GORMLEY, COLIN STEPHEN

				COMPONENT FORMED THEREIN	
<u>10324603</u>	<u>6818564</u>	150	12/20/2002	METHOD FOR ETCHING A TAPERED BORE IN A SILICON SUBSTRATE, AND A SEMICONDUCTOR WAFER COMPRISING THE SUBSTRATE	GORMLEY, COLIN STEPHEN
<u>10259188</u>	Not Issued	071	09/27/2002	FABRICATING COMPLEX MICRO-ELECTROMECHANICAL SYSTEMS USING A FLIP BONDING TECHNIQUE	GORMLEY, COLIN
<u>10259174</u>	Not Issued	061	09/27/2002	FABRICATING COMPLEX MICRO-ELECTROMECHANICAL SYSTEMS USING A DUMMY HANDLING SUBSTRATE	GORMLEY, COLIN
<u>10259173</u>	Not Issued	083	09/27/2002	FABRICATING COMPLEX MICRO-ELECTROMECHANICAL SYSTEMS USING AN INTERMEDIATE ELECTRODE LAYER	GORMLEY, COLIN
<u>10194392</u>	<u>6723579</u>	150	07/12/2002	SEMICONDUCTOR WAFER COMPRISING MICRO-MACHINED COMPONENTS AND A METHOD FOR FABRICATING THE SEMICONDUCTOR WAFER	GORMLEY, COLIN STEPHEN
<u>09661766</u>	<u>6797591</u>	150	09/14/2000	METHOD FOR FORMING A SEMICONDUCTOR DEVICE AND A SEMICONDUCTOR DEVICE FORMED BY THE METHOD	GORMLEY, COLIN STEPHEN

Inventor Search Completed: No Records to Display.

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	<input type="text" value="GORMLEY"/>	<input type="text" value="COLIN"/>	

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Day : Monday  
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 **PALM INTRANET****Inventor Name Search Result**

Your Search was:

Last Name = LIMB

First Name = SCOTT JONG

Application#	Patent#	Status	Date Filed	Title	Inventor Name 1
10617427	Not Issued	030	07/11/2003	METHOD FOR FORMING A MICRO-MECHANICAL COMPONENT IN A SEMICONDUCTOR WAFER, AND A SEMICONDUCTOR WAFER COMPRISING A MICRO-MECHANICAL COMPONENT FORMED THEREIN	LIMB, SCOTT JONG HO

**Inventor Search Completed: No Records to Display.**

**Search Another: Inventor**

<b>Last Name</b>	<b>First Name</b>	
<input type="text" value="LIMB"/>	<input type="text" value="SCOTT JONG"/>	<input type="button" value="Search"/>

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	Hits	Search Text	DBs	Time Stamp
1	2199	micro?mirror	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/28 13:17
2	13	micro?mirror and handle adj layer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/03 13:38
3	5	micro?mirror and through adj bore	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/03 13:26
4	21	micro?mirror and buried adj oxide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/03 13:28
5	13	micro?mirror and etch?stop	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/03 13:30
6	37	micro?mirror and support adj layer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/03 13:34
7	46	micro?mirror and photo?resist	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/03 13:35
8	232	micro?mirror and (photo?resist photoresist)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/03 13:36
9	13	micro?mirror and (photo?resist photoresist) same (trench trenches trenchs)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/03 13:36

	Hits	Search Text	DBs	Time Stamp
10	28	micro?mirror and (photo?resist photoresist) same (trench trenches trenchs opening hole)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/03 13:36
11	148	micro?mirror and membrane	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/03 13:39
12	55	micro?mirror and "438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/12/03 13:40
13	188	438/43.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/28 13:16
14	179	438/54.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/28 13:16
15	132	438/71.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/28 13:16
16	269	438/72.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/28 13:16
17	881	438/455.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/28 13:16
18	268	438/667.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/28 13:16

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19	713	438/701.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/28 13:16
20	847	359/291.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/28 13:17
21	259	359/578.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/28 13:17
22	208	359/847.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/28 13:17
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24	0	micro?mirror and S15	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/28 13:17
25	0	micro?mirror and S16	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/28 13:17
26	111	micro?mirror and S20	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/28 13:20
27	2	micro?mirror and S13	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/28 13:18

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29	2	micro?mirror and S18	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/28 13:19
30	1	micro?mirror and S19	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/28 13:19
31	7	micro?mirror and S21	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/28 13:19
32	2	micro?mirror and S22	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/28 13:20
33	1	micro?mirror and S20 and (liner or lining)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/28 13:21
34	4	micro?mirror and (hole trench opening via) with (liner or lining)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/28 13:23
35	13	micro?mirror and (liner or lining)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/28 13:23
36	40	perkins-pamela.xa.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/01/28 13:29

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